Second Quarter FY 2007

May / June 2007

Dr. Wolfgang Ziebart President & CEO



Disclaimer



This presentation was prepared as of April 27, 2007 and is current only as of that date.

This presentation includes forward-looking statements about the future of Infineon's business and the industry in which it operates. These include statements relating to future developments in the world semiconductor market, including the market for memory products, Infineon's future growth, the benefits of research and development alliances and activities, Infineon's planned levels of future investment in the expansion and modernization of its production capacity, the introduction of new technology at its facilities, the continuing transitioning of its production processes to smaller structure sizes, cost savings related to such transitioning and other initiatives, Infineon's successful development of technology based on industry standards, Infineon's ability to offer commercially viable products based on its technology, Infineon's ability to achieve its cost savings and growth targets, and the impact of the carve-out of Qimonda, the group's memory products business, its initial public offering, and any further sales of Qimonda shares or other corporate financing measures in that regard.

These forward-looking statements are subject to a number of uncertainties, including trends in demand and prices for semiconductors generally and for Infineon's products in particular, the success of Infineon's development efforts, both alone and with partners, the success of Infineon's efforts to introduce new production processes, the actions of competitors, the availability of funds for planned expansion efforts, and the outcome of antitrust investigations and litigation matters, as well as the other factors mentioned in this presentation and those described in the "Risk Factors" section of the annual report of Infineon on Form 20-F filed with the U.S. Securities and Exchange Commission on November 30, 2006 or contained in the company's quarterly reports. As a result, Infineon's actual results could differ materially from those contained in these forward-looking statements. You are cautioned not to place undue reliance on these forward-looking statements.

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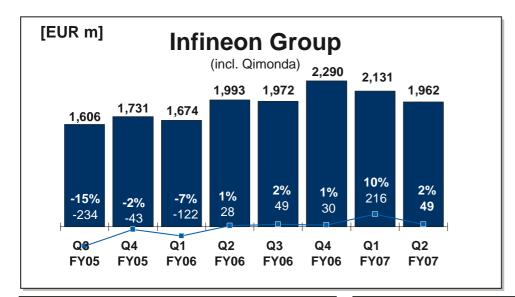
Group Financials and Targets

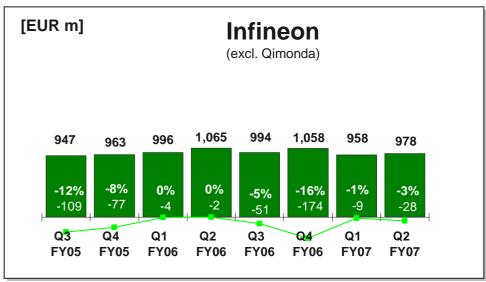
■ COM Growth Drivers, Products and Strategy

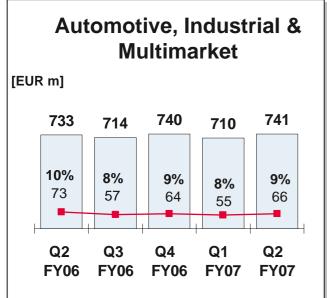
■ AIM Growth Drivers, Products and Strategy

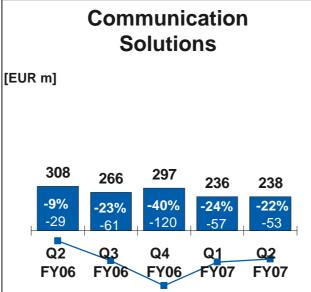
Second Quarter FY 2007 Results: Revenues of EUR 1.96 bn; EBIT of EUR 49 m

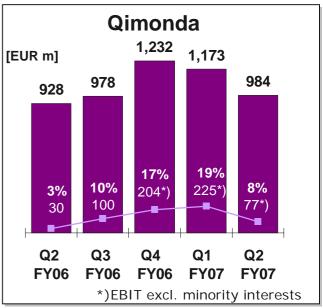












Infineon excl. Qimonda Third Quarter FY 2007 Outlook



IFX

Revenues and EBIT excluding Qimonda and before charges are expected to increase.

COM

- Revenues and EBIT to improve strongly q-o-q
- Significant revenue increase given ramp of platform shipments in wireless business; wireline business to be about flat

AIM

- Revenues and EBIT to remain at least flat q-o-q
- Auto to be up slightly; Industrial & Multimarket to be about flat; Security & ASIC to decrease

OOS, C & E

- Combined EBIT loss before charges broadly unchanged q-o-q
- Charges in the fiscal third quarter are expected to be insignificant

Infineon excl. Qimonda Group Results and FY 2007, FY 2008 Outlook



	FY 2005	FY 2006 ^{*)}	FY 2007	FY 2008			
in EUR m							
Sales	3,933	4,114					
Gross Profit (Gross margin)	1,187 <i>(30%)</i>	1,308 (32%)					
R&D	902	816	760-800				
SG&A	449	536	500-540				
				_			
EBIT (EBIT margin)	-305 (-8%)	-217 (-5%)					

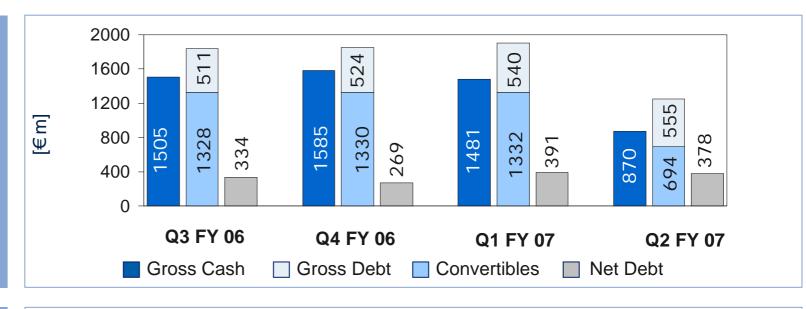
Infineon defines EBIT as Earnings (loss) Before Interest and Taxes.

^{*)} FY2006: Includes net charges of € 199 million relating primarily to various impairments and restructuring measures as well as expenses incurred in connection with the insolvency of BenQ Mobile Germany and the IPO of Qimonda.

Infineon excl. Qimonda Gross Cash, Gross Debt and Net Debt



Financial structure for the past quarters



CapEx and D&A

[€ m]	1Q FY07	2Q FY07	FY 2007	FY 2008+
CapEx /Sales (%)	105 11.0%	114 <i>11.7%</i>	450-550	10-12% of sales
D&A /Sales (%)	162 16.9%	152 15.5%	550-650	in line with CapEx

Infineon Businesses



Communication Solutions

Mobile Phone Platforms

Feature Phone

Entry Phone

Mobile Software

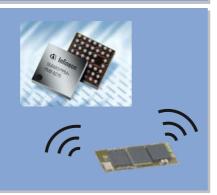


RF Solutions

RF Engine

Tuner Systems

RF Power



Broadband

Access



Automotive, Industrial & Multimarket

Automotive

Microcontroller

Automotive Power

Sense & Control



Industrial & Multimarket

Power Management & Drives

Discrete Semiconductors



Security & ASICs

ASIC Design & Security

Chip Card & Security ICs



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■ Group Financials and Targets

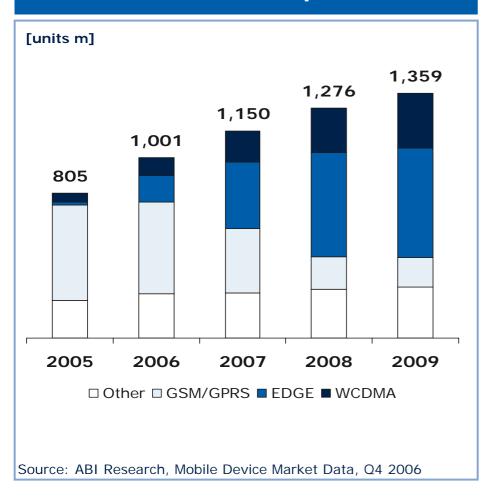
■ COM Growth Drivers, Products and Strategy

■ AIM Growth Drivers, Products and Strategy

Major COM Growth Opportunities: Mobile Phone Platforms



Market development



IFX content



Complete Mobile Phone Platform Solutions for Major Growth Markets



Target markets	2G / 2.5G GSM / GPRS		2.7 ED		3G UMTS	3.5G HSDPA	
Platform	ULC1	ULC2	MP-E	MP- Elite	MP-EU	MP-EH	
Baseband	Oradio	oice	✓	radio	✓	✓	
RF CMOS transceiver	E-GOLDradio	E-GOLDvoice	✓	-GOLDra	✓	✓	
Power management	✓	E-G	✓	S-G	✓	✓	
Protocol stack	✓	✓	✓	✓	✓	✓	
Ramp-up	\checkmark	✓	√	2H CY07	\checkmark	CY 2007+	

Integrated in one chip

Successful Launch of Platforms in Major Target Markets









Plus:

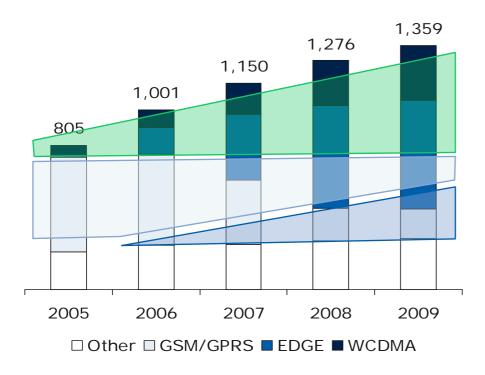
- Design win at NOKIA with E-GOLDvoice single-chip for entry level phones.
- Design wins across our ULC, EDGE and 3G platforms at other major customers.

Major COM Growth Opportunities: RF Transceiver



Market Development

Worldwide mobile phone shipments by air interface [mn]



RF Transceiver Segmentation

Innovative RF Engines

- Stand alone transceiver solutions
- Multi Bands, Multi Mode
- Size & power consumption critical
- Growing volume
- High Innovation
- High ASP (x3-x5 GSM/GPRS)

Commoditized RF Engines

- Stand alone transceiver solutions
- High Volume
- Cost competitive market

Single Chip

- Baseband + RF Integration
- · Handsets with fixed feature set
- Commodity
- Ultra Low Cost

Source: Strategy Analytics, 2006; IFX

RF Transceiver CMOS Leadership Turns Into Design-Wins



2G / 2.5G GSM / GPRS 2.75G **EDGE**

3G WCDMA

3.5G **HSDPA**

4G WiMAX / LTE

SMARTI SD SMARTI SD2

130nm CMOS

SMARTI PM SMARTI PM2 SMARTI PM+

130nm CMOS

SMARTi 3G **SMARTI 3GE**

130nm CMOS

SMARTI UE

130nm CMOS

SMARTI WIMAX

130nm CMOS

Customer	Air Interface			
two tier-1 OEMs	EDGE (SMARTi PM+)			
three tier-1 OEMs	WCDMA / WEDGE (SMARTI 3GE / 3G)			
tier-1 OEM	HEDGE (SMARTI UE)			
multiple DW on IFX platforms	EDGE / WEDGE / HEDGE			







Shipped more than 230m Cellular Tranceiver IC's in 2006

Nr.1 worldwide in **RF Transceivers**

World's first EDGE **CMOS RF Transceiver** in volume

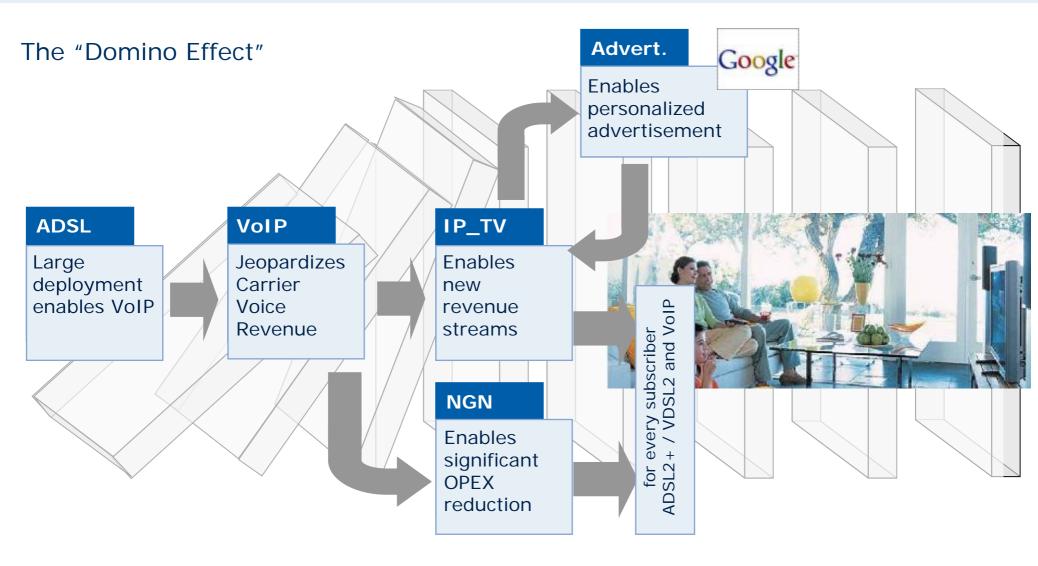


World's first WCDMA CMOS RF Transceiver in volume



Major COM Growth Driver: Broadband





Broadband Design-Win Momentum Continues



VDSL2 "VINAXTM"

- World's first VDSL2 RollOut with Deutsche Telekom on CO- and CPE-side in Germany continuous as planned
- Design-Wins in APAC and NAFTA for profile
 17a and 30a



ADSL2+
"GEMINAXTM-MAX"

- Design-Win at two customers based in APAC
- Major European customer



 Design-Win at major EU carrier for ADSI_IAD



VoIP "VINETICTM"

- Extension of customer & technology base by positioning VINTETICTM in alternative access technologies
- Major global customer



SHDSL.bis "SOCRATES®-4e"

Leading SLAM customers in Europe and Asia



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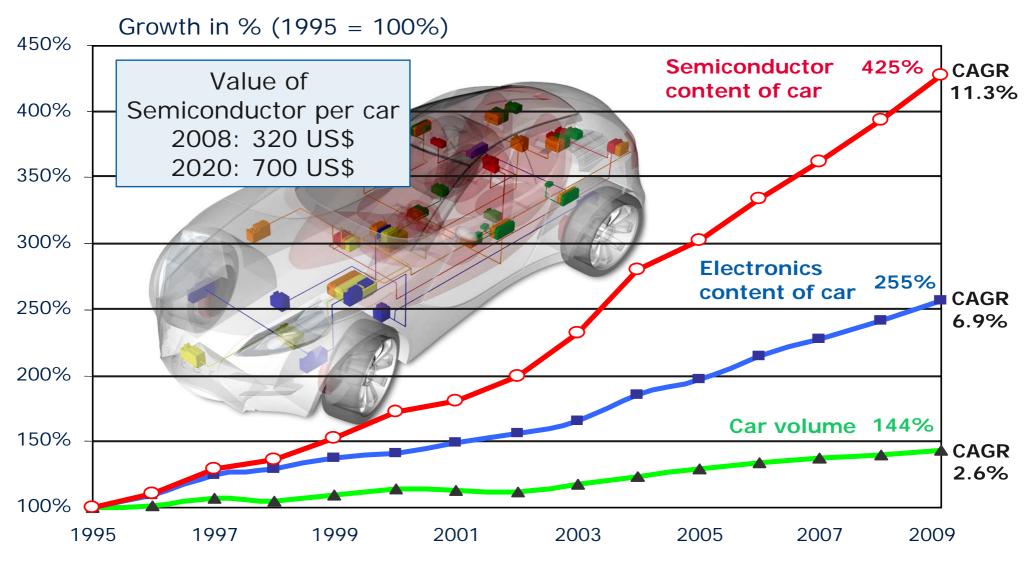
■ Group Financials and Targets

■ COM Growth Drivers, Products and Strategy

■ AIM Growth Drivers, Products and Strategy

Automotive Microelectronics Trends – More Than 50% of \$-value of Electronics is Semiconductors





Source: ZVEI

Areas of Growth in Automotive



Energy Efficiency

- Fuel consumption
- Energy recovery

Regulation

- Emission limits
- Safety (TPMS, emergency call, VSC)
- Toll collection

Driving Experience

- Comfort features
- Safety
- Proactive warning, assist and intervention

Emerging Markets

China and India



CAGR

5%

8%

11%

5%

25.8

4.2

7.2

8.1

6.3

2011

■ Infotainment

Safety

CAGR

7.4%

28%

31%

25%



Powertrain

- Airbag, ABS & VSC
- Driver assistance systems

- Electrical motor control
- LEDs for lighting

Infotainment

Integration of consumer devices into vehicle

[USD bn]

18%

27%

29%

26%

18.0

3.3

4.8

5.2

4.7

2006

Source: Strategy Analytics, 2006

■ Powertrain

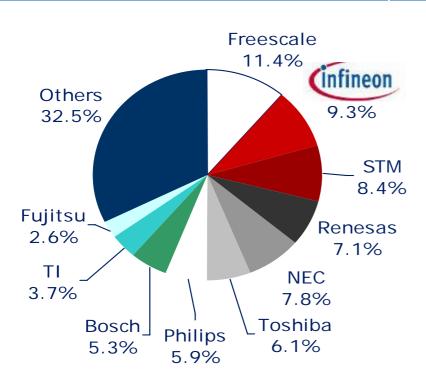
□ Body

Market

Infineon Automotive Ranks No. 2 Worldwide Continuously Outperforming the Market

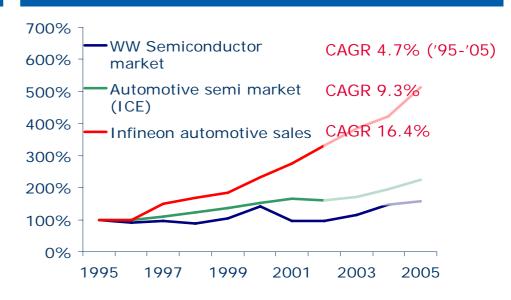


Infineon Automotive 2005*
No. 3 US No. 2 World No. 1 Europe



Market: USD 18,019 m** CAGR: 7.4% (2006-11)**

Continuous Outperformance

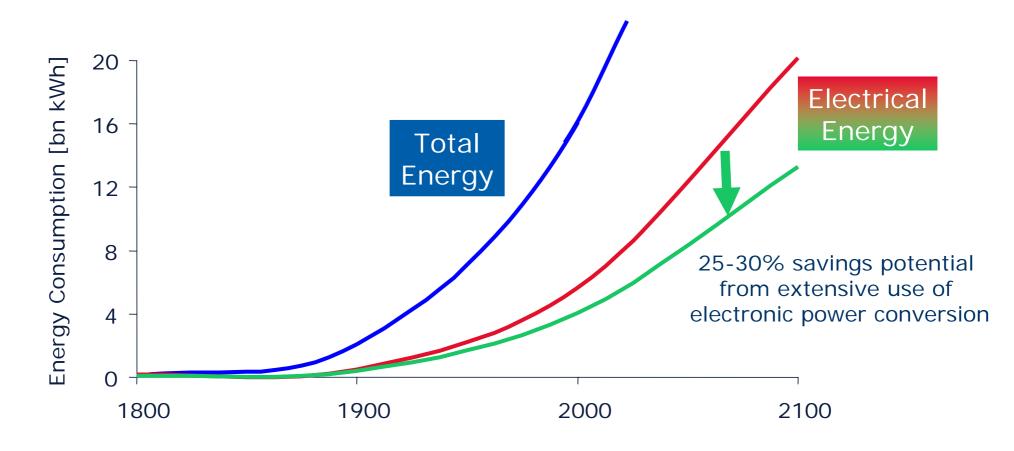


- Strong European market development compared to rest of world.
- Strengthened regional business in NAFTA/Japan.
- Improved relationships to major automotive system vendors.

Strong market position in Europe secures technological leadership.

Energy Demand and Electricity Consumption are on the Rise – We Can Help to "Do More With Less"





Savings of 25% are possible in current electrical energy consumption which equals the demand of the USA.

Today's Savings Potential from Using Electronic Power Conversion and Control



Stand-by power (TV)



~ 90% savings potential

Power supply in a Server



~ 12% savings potential

Lighting



~ 25% savings potential (electronic ballast)

Motor Control



30-40% savings potential (rpm control)

Traction Drives



20-30% savings potential (energy recuperation)

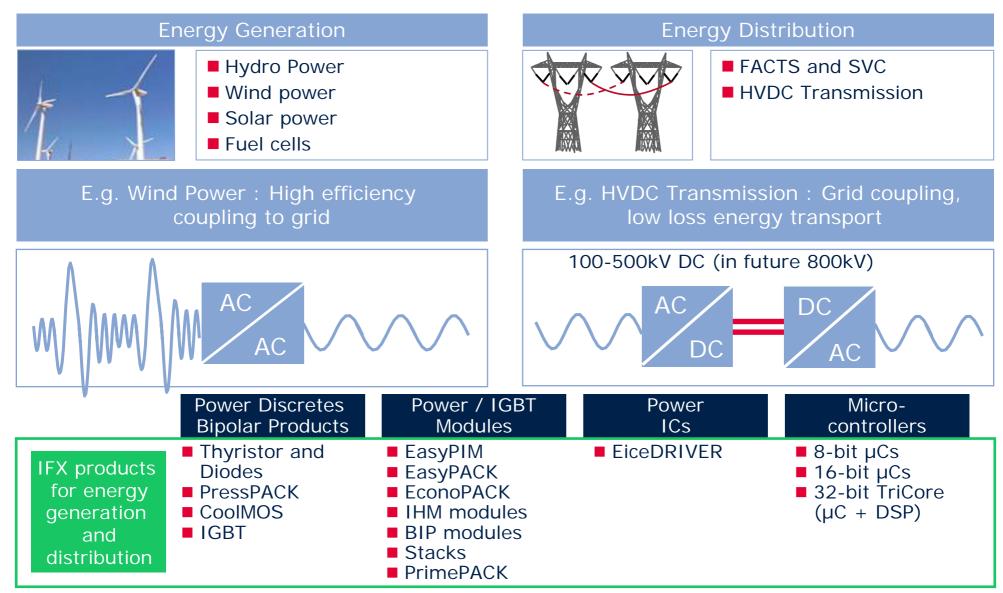
Climate Control



30-40% savings potential (improved control)

Energy Generation and Distribution Grid Coupling and Long Range Energy Transport





Energy Consumption Focus is on Efficient Power Conversion



Drives Applications Frequency Conversion

- Traction (trains)
- Speed controlled motors in
 - industrial
 - home
 - Pumps
- Automotive (Hybrids)



AC/DC Power Supplies

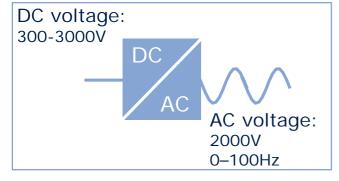
- Computer & server
- Adapter
- Charger
- TV, ĎVD, etc.
- Lighting
- Game console

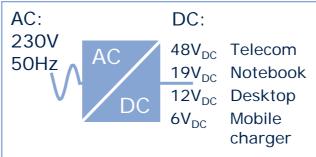


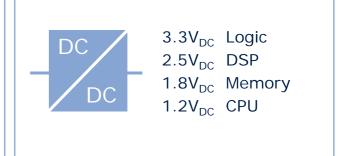
DC/DC Power Conversion

- Motherboard
- Graphics card
- Notebook
- Telecom
- VRMs
- Server









Power Discretes Bipolar Products

- CoolMOS
- thinQ! family (SiC Diode)
- Highspeed IGBTs
- OptiMOS

Power / IGBT Modules

- wodules
- EasyPIM
- EasyPACK
- IsoPACK
- EconoPACK
- Thyristor / Diode modules

Power ICs

- PWM & PFC ICs
- CoolSET
- Integrated switches
- Gate drivers
- Smart ballast
- EiceDRIVER

Microcontrollers

- 8-bit µCs
- 16-bit µCs
- 32-bit TriCore

 $(\mu C + DSP)$

27-April-2007

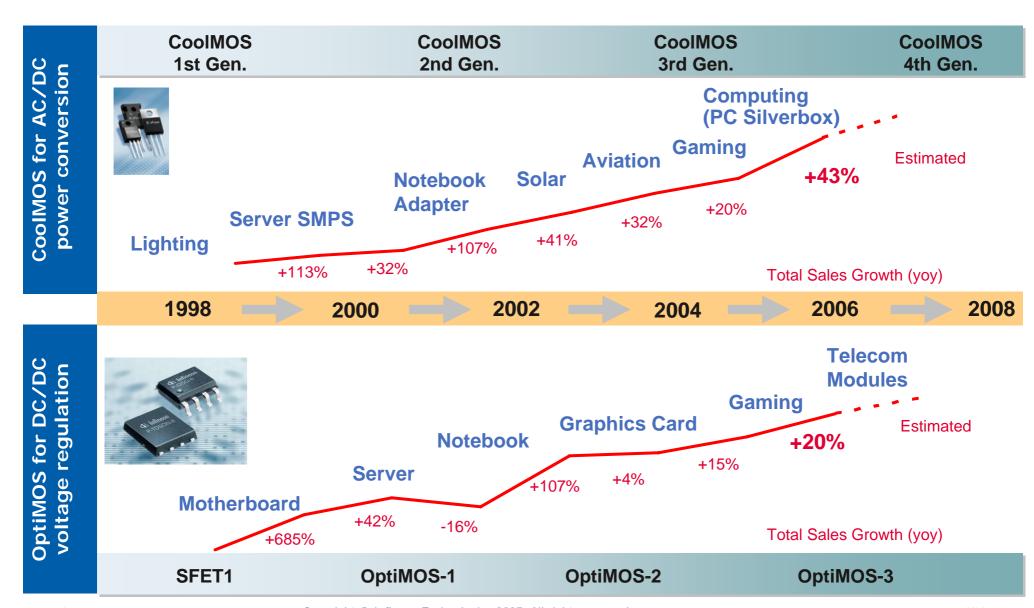
IFX products

Infineon – Never stop thinking



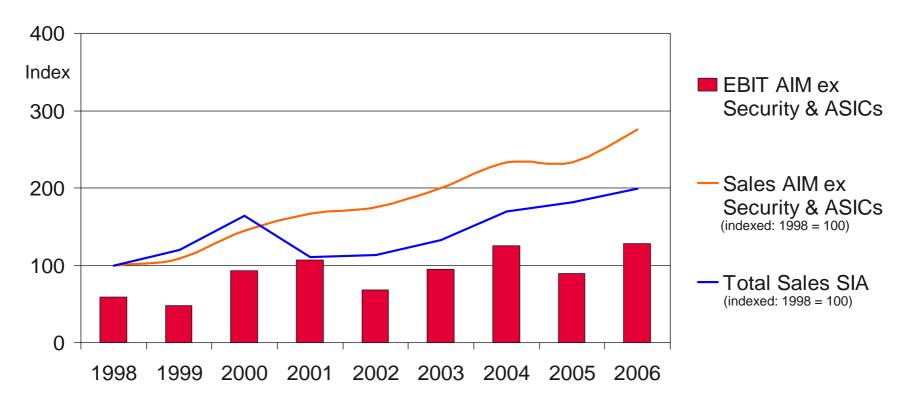
Growth Driver for CoolMOS / OptiMOS: More Applications Require Power Efficiency





Profitable Growth: Infineon's AIM ex Security & ASICs*













Key Financials



	Q3 F05	Q4 F05	Q1 F06	Q2 F06	Q3 F06	Q4 F06	Q1 F07	Q2 F07
Sales (EUR m)	947	964	996	1,065	995	1,058	958	978
EBIT (EUR m) EBIT margin	-98 -10.3%	-81 - <i>8.4%</i>	1 <i>0.1%</i>	7 0.7%	-51 -5.1%	-174 -16.4%	-9 -0.9%	-28 -2.9%
EBIT ex charges (EUR m) EBIT margin ex charges	-27 -2.9%	-8 -0.8%	3 <i>0.3%</i>	11 1.0%	-22 -2.2%	-11 -1.0%	-9 <i>-0.9%</i>	1 <i>0.1%</i>
D&A (EUR m) D&A / Sales (%)	168 <i>17.7%</i>	208 21.6%	150 15.1%	206 19.3%	174 17.5%	172 16.3%	162 16.9%	152 15.5%
CapEx (EUR m) CapEx / Sales (%)	NM <i>NA</i>	107 11.1%	49 <i>4.9%</i>	314 <i>29.5%</i>	158 <i>15.9%</i>	173 <i>16.4%</i>	105 <i>11.0%</i>	114 <i>11.7%</i>
Gross Cash (EUR m)		1,374	1,264	1,426	1,427	1,585	1,481	870
Gross Debt (EUR m)		1,557	1,593	1,872	1,839	1,854	1,872	1,248
Net debt (EUR m)		183	329	446	412	269	391	378
Employees		26,834	30,561		29,446	29,849	30,071	29,871

Financial Calendar



- Jul 27, 2007* Interim Report FQ3 2007
- Nov 14, 2007* Interim Report FQ4 2007

* = Preliminary Date